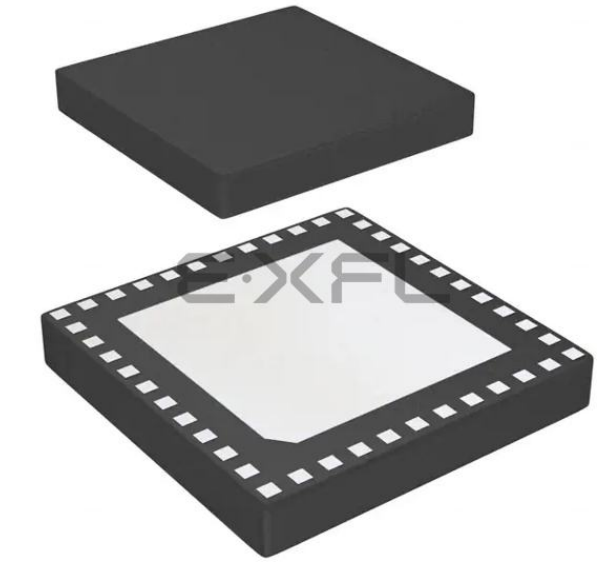
Microchip Technology - PIC32MX150F128D-50I/TL Datasheet



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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	MIPS32® M4K™
Core Size	32-Bit Single-Core
Speed	50MHz
Connectivity	I²C, IrDA, LINbus, PMP, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, I²S, POR, PWM, WDT
Number of I/O	35
Program Memory Size	128KB (128K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	32K x 8
Voltage - Supply (Vcc/Vdd)	2.3V ~ 3.6V
Data Converters	A/D 13x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-VFTLA Exposed Pad
Supplier Device Package	44-VTLA (6x6)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic32mx150f128d-50i-tl

TABLE 1-1: PINOUT I/O DESCRIPTIONS (CONTINUED)

Pin Name	Pin Number[1]				Pin Type	Buffer Type	Description
	28-pin QFN	28-pin SSOP/ SPDIP/ SOIC	36-pin VTLA	44-pin QFN/ TQFP/ VTLA			
SDA1	15	18	19	1	I/O	ST	Synchronous serial data input/output for I2C1
SCL2	4	7	2	24	I/O	ST	Synchronous serial clock input/output for I2C2
SDA2	3	6	1	23	I/O	ST	Synchronous serial data input/output for I2C2
TMS	19[2] 11[3]	22[2] 14[3]	25[2] 15[3]	12	I	ST	JTAG Test mode select pin
TCK	14	17	18	13	I	ST	JTAG test clock input pin
TDI	13	16	17	35	O	—	JTAG test data input pin
TDO	15	18	19	32	O	—	JTAG test data output pin
RTCC	4	7	2	24	O	ST	Real-Time Clock alarm output
CVREF-	28	3	34	20	I	Analog	Comparator Voltage Reference (low)
CVREF+	27	2	33	19	I	Analog	Comparator Voltage Reference (high)
CVREFOUT	22	25	28	14	O	Analog	Comparator Voltage Reference output
C1INA	4	7	2	24	I	Analog	Comparator Inputs
C1INB	3	6	1	23	I	Analog	
C1INC	2	5	36	22	I	Analog	
C1IND	1	4	35	21	I	Analog	
C2INA	2	5	36	22	I	Analog	
C2INB	1	4	35	21	I	Analog	
C2INC	4	7	2	24	I	Analog	
C2IND	3	6	1	23	I	Analog	
C3INA	23	26	29	15	I	Analog	
C3INB	22	25	28	14	I	Analog	
C3INC	27	2	33	19	I	Analog	
C3IND	1	4	35	21	I	Analog	
C1OUT	PPS	PPS	PPS	PPS	O	—	Comparator Outputs
C2OUT	PPS	PPS	PPS	PPS	O	—	
C3OUT	PPS	PPS	PPS	PPS	O	—	

Legend: CMOS = CMOS compatible input or output; Analog = Analog input; P = Power
ST = Schmitt Trigger input with CMOS levels; O = Output; I = Input
TTL = TTL input buffer; PPS = Peripheral Pin Select; — = N/A

Note 1: Pin numbers are provided for reference only. See the **"Pin Diagrams"** section for device pin availability.

2: Pin number for PIC32MX1XX devices only.

3: Pin number for PIC32MX2XX devices only.

TABLE 1-1: PINOUT I/O DESCRIPTIONS (CONTINUED)

Pin Name	Pin Number[1]				Pin Type	Buffer Type	Description
	28-pin QFN	28-pin SSOP/ SPDIP/ SOIC	36-pin VTLA	44-pin QFN/ TQFP/ VTLA			
USBID	11[3]	14[3]	15[3]	41[3]	I	ST	USB OTG ID detect
CTED1	27	2	33	19	I	ST	CTMU External Edge Input
CTED2	28	3	34	20	I	ST	
CTED3	13	16	17	43	I	ST	
CTED4	15	18	19	1	I	ST	
CTED5	22	25	28	14	I	ST	
CTED6	23	26	29	15	I	ST	
CTED7	—	—	20	5	I	ST	
CTED8	—	—	—	13	I	ST	
CTED9	9	12	10	34	I	ST	
CTED10	14	17	18	44	I	ST	
CTED11	18	21	24	8	I	ST	
CTED12	2	5	36	22	I	ST	
CTED13	3	6	1	23	I	ST	
CTPLS	21	24	27	11	O	—	CTMU Pulse Output
PGED1	1	4	35	21	I/O	ST	Data I/O pin for Programming/Debugging Communication Channel 1
PGEC1	2	5	36	22	I	ST	Clock input pin for Programming/Debugging Communication Channel 1
PGED2	18	21	24	8	I/O	ST	Data I/O pin for Programming/Debugging Communication Channel 2
PGEC2	19	22	25	9	I	ST	Clock input pin for Programming/Debugging Communication Channel 2
PGED3	11[2]	14[2]	15[2]	41[2]	I/O	ST	Data I/O pin for Programming/Debugging Communication Channel 3
	27[3]	2[3]	33[3]	19[3]			
PGEC3	12[2]	15[2]	16[2]	42[2]	I	ST	Clock input pin for Programming/ Debugging Communication Channel 3
	28[3]	3[3]	34[3]	20[3]			
PGED4	—	—	3	12	I/O	ST	Data I/O pin for Programming/Debugging Communication Channel 4
PGEC4	—	—	4	13	I	ST	Clock input pin for Programming/ Debugging Communication Channel 4

Legend: CMOS = CMOS compatible input or output; Analog = Analog input; P = Power
ST = Schmitt Trigger input with CMOS levels; O = Output; I = Input
TTL = TTL input buffer; PPS = Peripheral Pin Select; — = N/A

Note 1: Pin numbers are provided for reference only. See the **"Pin Diagrams"** section for device pin availability.

2: Pin number for PIC32MX1XX devices only.

3: Pin number for PIC32MX2XX devices only.

3.0 CPU

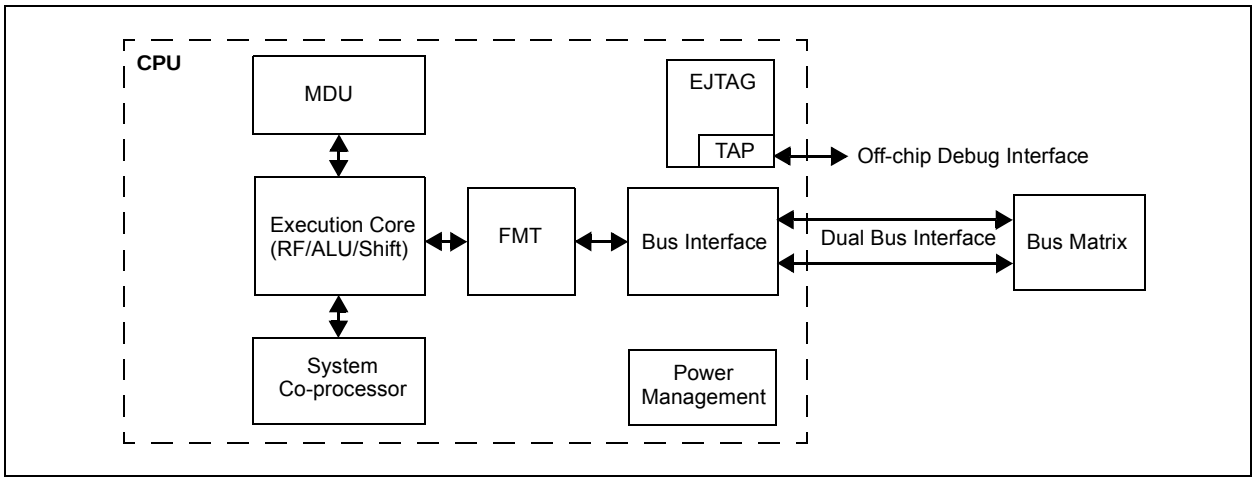
Note: This data sheet summarizes the features of the PIC32MX1XX/2XX 28/36/44-pin Family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 2. "CPU"** (DS60001113), which is available from the *Documentation > Reference Manual* section of the Microchip PIC32 web site (www.microchip.com/pic32). Resources for the MIPS32® M4K® Processor Core are available at: www.imgtec.com.

The MIPS32® M4K® Processor Core is the heart of the PIC32MX1XX/2XX family processor. The CPU fetches instructions, decodes each instruction, fetches source operands, executes each instruction and writes the results of instruction execution to the destinations.

3.1 Features

- 5-stage pipeline
- 32-bit address and data paths
- MIPS32 Enhanced Architecture (Release 2)
  - Multiply-accumulate and multiply-subtract instructions
  - Targeted multiply instruction
  - Zero/One detect instructions
  - `WAIT` instruction
  - Conditional move instructions (`MOVN`, `MOVZ`)
  - Vectored interrupts
  - Programmable exception vector base
  - Atomic interrupt enable/disable
  - Bit field manipulation instructions
- MIPS16e® code compression
  - 16-bit encoding of 32-bit instructions to improve code density
  - Special PC-relative instructions for efficient loading of addresses and constants
  - `SAVE` and `RESTORE` macro instructions for setting up and tearing down stack frames within subroutines
  - Improved support for handling 8 and 16-bit data types
- Simple Fixed Mapping Translation (FMT) mechanism
- Simple dual bus interface
  - Independent 32-bit address and data buses
  - Transactions can be aborted to improve interrupt latency
- Autonomous multiply/divide unit
  - Maximum issue rate of one 32x16 multiply per clock
  - Maximum issue rate of one 32x32 multiply every other clock
  - Early-in iterative divide. Minimum 11 and maximum 33 clock latency (dividend (*rs*) sign extension-dependent)
- Power control
  - Minimum frequency: 0 MHz
  - Low-Power mode (triggered by `WAIT` instruction)
  - Extensive use of local gated clocks
- EJTAG debug and instruction trace
  - Support for single stepping
  - Virtual instruction and data address/value
  - Breakpoints

FIGURE 3-1: MIPS32® M4K® PROCESSOR CORE BLOCK DIAGRAM



3.2 Architecture Overview

The MIPS32 M4K processor core contains several logic blocks working together in parallel, providing an efficient high-performance computing engine. The following blocks are included with the core:

- Execution Unit
- Multiply/Divide Unit (MDU)
- System Control Coprocessor (CP0)
- Fixed Mapping Translation (FMT)
- Dual Internal Bus interfaces
- Power Management
- MIPS16e® Support
- Enhanced JTAG (EJTAG) Controller

3.2.1 EXECUTION UNIT

The MIPS32 M4K processor core execution unit implements a load/store architecture with single-cycle ALU operations (logical, shift, add, subtract) and an autonomous multiply/divide unit. The core contains thirty-two 32-bit General Purpose Registers (GPRs) used for integer operations and address calculation. The register file consists of two read ports and one write port and is fully bypassed to minimize operation latency in the pipeline.

The execution unit includes:

- 32-bit adder used for calculating the data address
- Address unit for calculating the next instruction address
- Logic for branch determination and branch target address calculation
- Load aligner
- Bypass multiplexers used to avoid stalls when executing instruction streams where data producing instructions are followed closely by consumers of their results
- Leading Zero/One detect unit for implementing the `CLZ` and `CLO` instructions
- Arithmetic Logic Unit (ALU) for performing bitwise logical operations
- Shifter and store aligner

3.2.2 MULTIPLY/DIVIDE UNIT (MDU)

The MIPS32 M4K processor core includes a Multiply/Divide Unit (MDU) that contains a separate pipeline for multiply and divide operations. This pipeline operates in parallel with the Integer Unit (IU) pipeline and does not stall when the IU pipeline stalls. This allows MDU operations to be partially masked by system stalls and/or other integer unit instructions.

The high-performance MDU consists of a 32x16 booth recoded multiplier, result/accumulation registers (HI and LO), a divide state machine, and the necessary multiplexers and control logic. The first number shown ('32' of 32x16) represents the *rs* operand. The second number ('16' of 32x16) represents the *rt* operand. The PIC32 core only checks the value of the latter (*rt)* operand to determine how many times the operation must pass through the multiplier. The 16x16 and 32x16 operations pass through the multiplier once. A 32x32 operation passes through the multiplier twice.

The MDU supports execution of one 16x16 or 32x16 multiply operation every clock cycle; 32x32 multiply operations can be issued every other clock cycle. Appropriate interlocks are implemented to stall the issuance of back-to-back 32x32 multiply operations. The multiply operand size is automatically determined by logic built into the MDU.

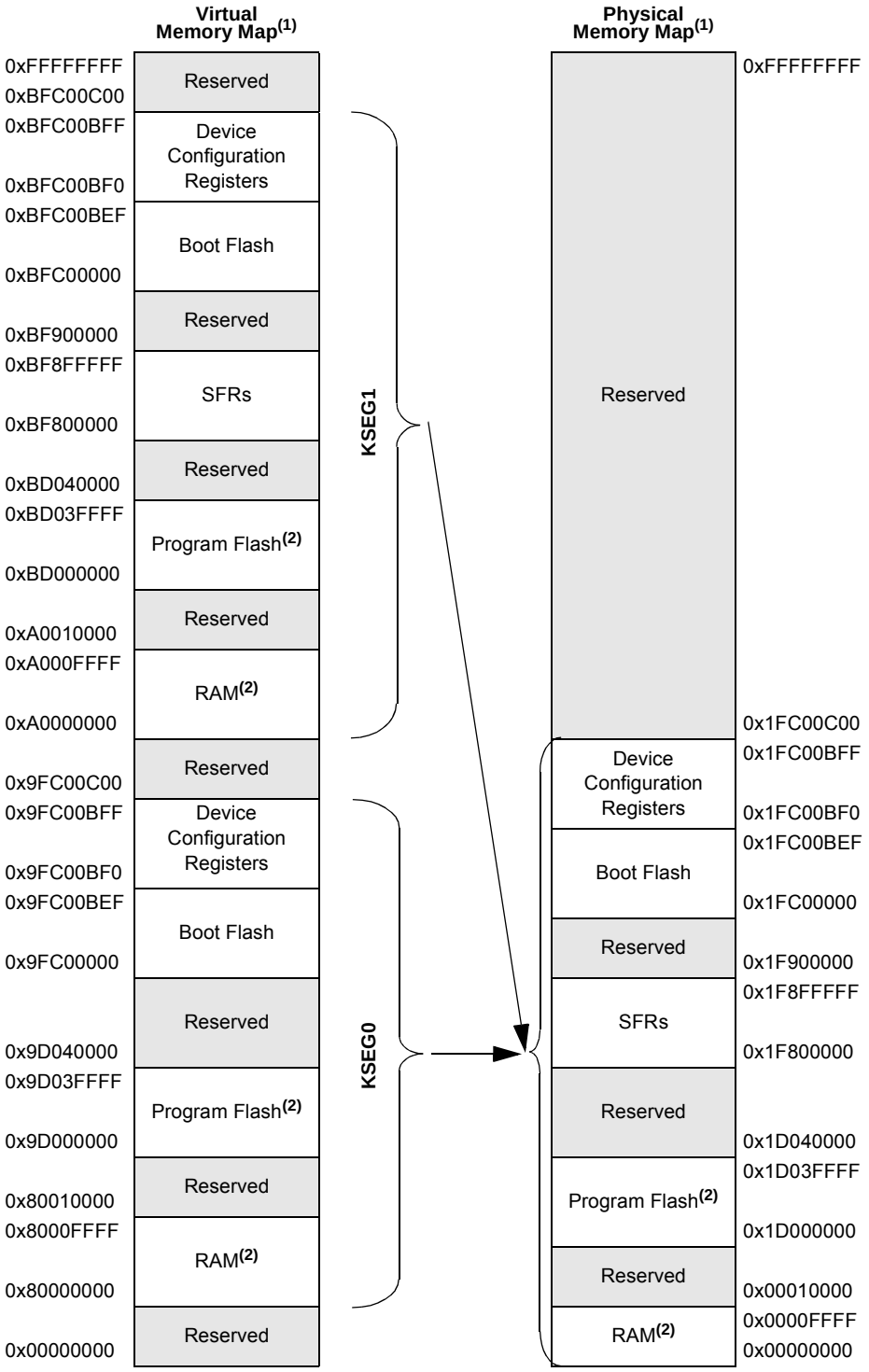
Divide operations are implemented with a simple 1 bit per clock iterative algorithm. An early-in detection checks the sign extension of the dividend (*rs*) operand. If *rs* is 8 bits wide, 23 iterations are skipped. For a 16-bit wide *rs*, 15 iterations are skipped and for a 24-bit wide *rs*, 7 iterations are skipped. Any attempt to issue a subsequent `MDU` instruction while a divide is still active causes an IU pipeline stall until the divide operation is completed.

Table 3-1 lists the repeat rate (peak issue rate of cycles until the operation can be reissued) and latency (number of cycles until a result is available) for the PIC32 core multiply and divide instructions. The approximate latency and repeat rates are listed in terms of pipeline clocks.

TABLE 3-1: MIPS32® M4K® PROCESSOR CORE HIGH-PERFORMANCE INTEGER MULTIPLY/DIVIDE UNIT LATENCIES AND REPEAT RATES

Opcode	Operand Size (mul *rt*) (div *rs*)	Latency	Repeat Rate
`MULT/MULTU, MADD/MADDU, MSUB/MSUBU`	16 bits	1	1
	32 bits	2	2
`MUL`	16 bits	2	1
	32 bits	3	2
`DIV/DIVU`	8 bits	12	11
	16 bits	19	18
	24 bits	26	25
	32 bits	33	32

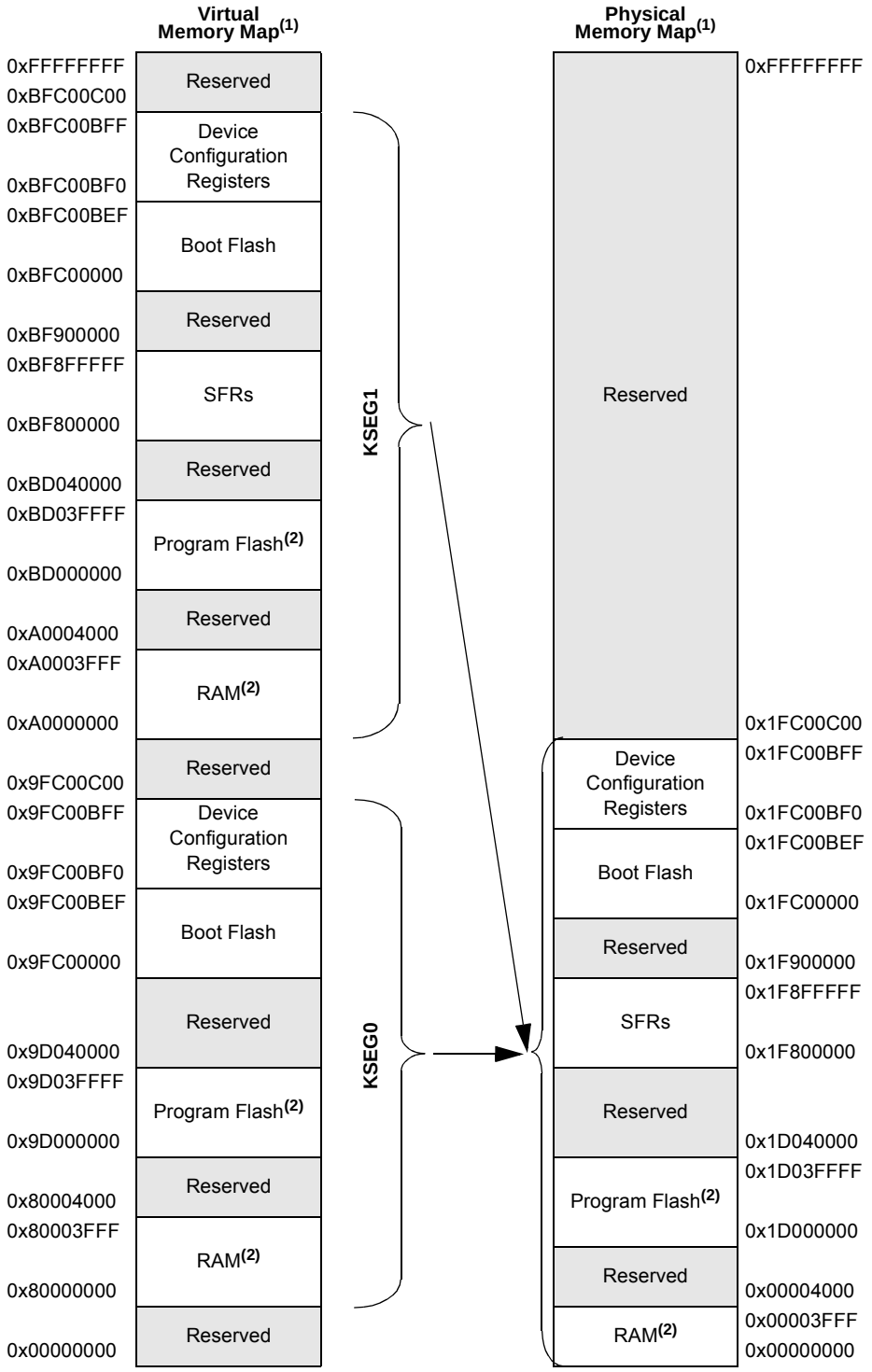
FIGURE 4-5: MEMORY MAP ON RESET FOR PIC32MX170/270 DEVICES (64 KB RAM, 256 KB FLASH)



Note 1: Memory areas are not shown to scale.

2: The size of this memory region is programmable (see **Section 3. "Memory Organization"** (DS60001115) in the *"PIC32 Family Reference Manual"*) and can be changed by initialization code provided by end-user development tools (refer to the specific development tool documentation for information).

FIGURE 4-6: MEMORY MAP ON RESET FOR PIC32MX130/230 DEVICES (16 KB RAM, 256 KB FLASH)



Note 1: Memory areas are not shown to scale.

2: The size of this memory region is programmable (see **Section 3. "Memory Organization"** (DS60001115) in the *"PIC32 Family Reference Manual"*) and can be changed by initialization code provided by end-user development tools (refer to the specific development tool documentation for information).

7.1 Interrupt Control Registers

TABLE 7-2: INTERRUPT REGISTER MAP

Virtual Address (BF88_#)	Register Name(1)	Bit Range	Bits																All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
1000	INTCON	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	MVEC	—	TPC<2:0>			—	—	—	INT4EP	INT3EP	INT2EP	INT1EP	INT0EP	0000
1010	INTSTAT(3)	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	SRIPL<2:0>			—	—	VEC<5:0>						0000
1020	IPTMR	31:16	IPTMR<31:0>																0000
		15:0																	0000
1030	IFS0	31:16	FCEIF	RTCCIF	FSCMIF	AD1IF	OC5IF	IC5IF	IC5EIF	T5IF	INT4IF	OC4IF	IC4IF	IC4EIF	T4IF	INT3IF	OC3IF	IC3IF	0000
		15:0	IC3EIF	T3IF	INT2IF	OC2IF	IC2IF	IC2EIF	T2IF	INT1IF	OC1IF	IC1IF	IC1EIF	T1IF	INT0IF	CS1IF	CS0IF	CTIF	0000
1040	IFS1	31:16	DMA3IF	DMA2IF	DMA1IF	DMA0IF	CTMUIF	I2C2MIF	I2C2SIF	I2C2BIF	U2TXIF	U2RXIF	U2EIF	SPI2TXIF	SPI2RXIF	SPI2EIF	PMPEIF	PMPIF	0000
		15:0	CNCIF	CNBIF	CNAIF	I2C1MIF	I2C1SIF	I2C1BIF	U1TXIF	U1RXIF	U1EIF	SPI1TXIF	SPI1RXIF	SPI1EIF	USBIF(2)	CMP3IF	CMP2IF	CMP1IF	0000
1060	IEC0	31:16	FCEIE	RTCCIE	FSCMIE	AD1IE	OC5IE	IC5IE	IC5EIE	T5IE	INT4IE	OC4IE	IC4IE	IC4EIE	T4IE	INT3IE	OC3IE	IC3IE	0000
		15:0	IC3EIE	T3IE	INT2IE	OC2IE	IC2IE	IC2EIE	T2IE	INT1IE	OC1IE	IC1IE	IC1EIE	T1IE	INT0IE	CS1IE	CS0IE	CTIE	0000
1070	IEC1	31:16	DMA3IE	DMA2IE	DMA1IE	DMA0IE	CTMUIE	I2C2MIE	I2C2SIE	I2C2BIE	U2TXIE	U2RXIE	U2EIE	SPI2TXIE	SPI2RXIE	SPI2EIE	PMPEIE	PMPIE	0000
		15:0	CNCIE	CNBIE	CNAIE	I2C1MIE	I2C1SIE	I2C1BIE	U1TXIE	U1RXIE	U1EIE	SPI1TXIE	SPI1RXIE	SPI1EIE	USBIE(2)	CMP3IE	CMP2IE	CMP1IE	0000
1090	IPC0	31:16	—	—	—	INT0IP<2:0>			INT0IS<1:0>		—	—	—	CS1IP<2:0>			CS1IS<1:0>		0000
		15:0	—	—	—	CS0IP<2:0>			CS0IS<1:0>		—	—	—	CTIP<2:0>			CTIS<1:0>		0000
10A0	IPC1	31:16	—	—	—	INT1IP<2:0>			INT1IS<1:0>		—	—	—	OC1IP<2:0>			OC1IS<1:0>		0000
		15:0	—	—	—	IC1IP<2:0>			IC1IS<1:0>		—	—	—	T1IP<2:0>			T1IS<1:0>		0000
10B0	IPC2	31:16	—	—	—	INT2IP<2:0>			INT2IS<1:0>		—	—	—	OC2IP<2:0>			OC2IS<1:0>		0000
		15:0	—	—	—	IC2IP<2:0>			IC2IS<1:0>		—	—	—	T2IP<2:0>			T2IS<1:0>		0000
10C0	IPC3	31:16	—	—	—	INT3IP<2:0>			INT3IS<1:0>		—	—	—	OC3IP<2:0>			OC3IS<1:0>		0000
		15:0	—	—	—	IC3IP<2:0>			IC3IS<1:0>		—	—	—	T3IP<2:0>			T3IS<1:0>		0000
10D0	IPC4	31:16	—	—	—	INT4IP<2:0>			INT4IS<1:0>		—	—	—	OC4IP<2:0>			OC4IS<1:0>		0000
		15:0	—	—	—	IC4IP<2:0>			IC4IS<1:0>		—	—	—	T4IP<2:0>			T4IS<1:0>		0000
10E0	IPC5	31:16	—	—	—	AD1IP<2:0>			AD1IS<1:0>		—	—	—	OC5IP<2:0>			OC5IS<1:0>		0000
		15:0	—	—	—	IC5IP<2:0>			IC5IS<1:0>		—	—	—	T5IP<2:0>			T5IS<1:0>		0000
10F0	IPC6	31:16	—	—	—	CMP1IP<2:0>			CMP1IS<1:0>		—	—	—	FCEIP<2:0>			FCEIS<1:0>		0000
		15:0	—	—	—	RTCCIP<2:0>			RTCCIS<1:0>		—	—	—	FSCMIP<2:0>			FSCMIS<1:0>		0000

Legend: x = unknown value on Reset; — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: With the exception of those noted, all registers in this table have corresponding CLR, SET and INV registers at their virtual addresses, plus offsets of 0x4 0x8 and 0xC, respectively. See **Section 11.2 "CLR, SET and INV Registers"** for more information.

2: These bits are not available on PIC32MX1XX devices.

3: This register does not have associated CLR, SET, INV registers.

REGISTER 8-1: OSCCON: OSCILLATOR CONTROL REGISTER

bit 3 **CF:** Clock Fail Detect bit
- 1 = FSCM has detected a clock failure
- 0 = No clock failure has been detected

bit 2 **UFRCEN:** USB FRC Clock Enable bit(1)
- 1 = Enable the FRC as the clock source for the USB clock source
- 0 = Use the Primary Oscillator or USB PLL as the USB clock source

bit 1 **SOSCEN:** Secondary Oscillator (SOSC) Enable bit
- 1 = Enable the Secondary Oscillator
- 0 = Disable the Secondary Oscillator

bit 0 **OSWEN:** Oscillator Switch Enable bit
- 1 = Initiate an oscillator switch to selection specified by NOSC<2:0> bits
- 0 = Oscillator switch is complete

Note 1: This bit is only available on PIC32MX2XX devices.

Note:	Writes to this register require an unlock sequence. Refer to **Section 6. "Oscillator"** (DS60001112) in the *"PIC32 Family Reference Manual"* for details.

REGISTER 9-1: DMACON: DMA CONTROLLER CONTROL REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	R/W-0	U-0	U-0	R/W-0	R/W-0	U-0	U-0	U-0
	ON(1)	—	—	SUSPEND	DMABUSY	—	—	—
7:0	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-16 **Unimplemented:** Read as '0'

bit 15 **ON:** DMA On bit(1)
- 1 = DMA module is enabled
- 0 = DMA module is disabled

bit 14-13 **Unimplemented:** Read as '0'

bit 12 **SUSPEND:** DMA Suspend bit
- 1 = DMA transfers are suspended to allow CPU uninterrupted access to data bus
- 0 = DMA operates normally

bit 11 **DMABUSY:** DMA Module Busy bit
- 1 = DMA module is active
- 0 = DMA module is disabled and not actively transferring data

bit 10-0 **Unimplemented:** Read as '0'

Note 1: When using 1:1 PBCLK divisor, the user's software should not read/write the peripheral's SFRs in the SYSCLK cycle immediately following the instruction that clears the module's ON bit.

TABLE 11-7: PERIPHERAL PIN SELECT OUTPUT REGISTER MAP

Virtual Address (BF80_#)	Register Name	Bit Range	Bits															All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
FB00	RPA0R	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	RPA0<3:0>				0000
FB04	RPA1R	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	RPA1<3:0>				0000
FB08	RPA2R	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	RPA2<3:0>				0000
FB0C	RPA3R	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	RPA3<3:0>				0000
FB10	RPA4R	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	RPA4<3:0>				0000
FB20	RPA8R(1)	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	RPA8<3:0>				0000
FB24	RPA9R(1)	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	RPA9<3:0>				0000
FB2C	RPB0R	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	RPB0<3:0>				0000
FB30	RPB1R	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	RPB1<3:0>				0000
FB34	RPB2R	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	RPB2<3:0>				0000
FB38	RPB3R	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	RPB3<3:0>				0000
FB3C	RPB4R	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	RPB4<3:0>				0000
FB40	RPB5R	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	RPB5<3:0>				0000
FB44	RPB6R(2)	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	RPB6<3:0>				0000
FB48	RPB7R	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	RPB7<3:0>				0000

Legend: x = unknown value on Reset; — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: This register is only available on 44-pin devices.
2: This register is only available on PIC32MX1XX devices.
3: This register is only available on 36-pin and 44-pin devices.

12.0 TIMER1

Note: This data sheet summarizes the features of the PIC32MX1XX/2XX 28/36/44-pin Family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 14. "Timers"** (DS60001105), which is available from the *Documentation > Reference Manual* section of the Microchip PIC32 web site (www.microchip.com/pic32).

This family of PIC32 devices features one synchronous/asynchronous 16-bit timer that can operate as a free-running interval timer for various timing applications and counting external events. This timer can also be used with the Low-Power Secondary Oscillator (SOSC) for Real-Time Clock (RTC) applications.

The following modes are supported:

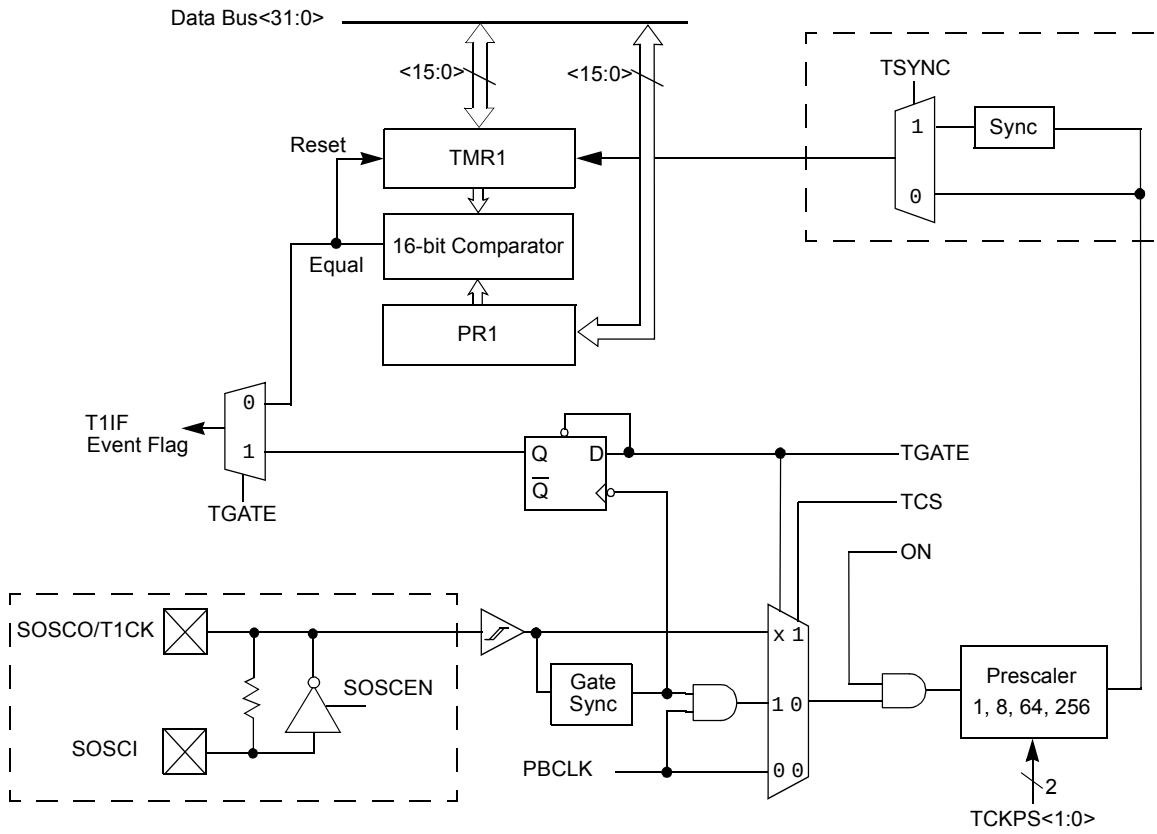
- Synchronous Internal Timer
- Synchronous Internal Gated Timer
- Synchronous External Timer
- Asynchronous External Timer

12.1 Additional Supported Features

- Selectable clock prescaler
- Timer operation during CPU Idle and Sleep mode
- Fast bit manipulation using CLR, SET and INV registers
- Asynchronous mode can be used with the SOSC to function as a Real-Time Clock (RTC)

Figure 12-1 illustrates a general block diagram of Timer1.

FIGURE 12-1: TIMER1 BLOCK DIAGRAM



Note: The default state of the SOSCEN (OSCCON<1>) bit during a device Reset is controlled by the FSOSCEN bit in Configuration Word, DEVCFG1.

15.0 INPUT CAPTURE

Note: This data sheet summarizes the features of the PIC32MX1XX/2XX 28/36/44-pin Family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 15. "Input Capture"** (DS60001122), which is available from the *Documentation > Reference Manual* section of the Microchip PIC32 web site (www.microchip.com/pic32).

The Input Capture module is useful in applications requiring frequency (period) and pulse measurement.

The Input Capture module captures the 16-bit or 32-bit value of the selected Time Base registers when an event occurs at the ICx pin. The following events cause capture events:

- Simple capture event modes:
  - Capture timer value on every rising and falling edge of input at ICx pin
  - Capture timer value on every edge (rising and falling)
  - Capture timer value on every edge (rising and falling), specified edge first.
- Prescaler capture event modes:
  - Capture timer value on every 4th rising edge of input at ICx pin
  - Capture timer value on every 16th rising edge of input at ICx pin

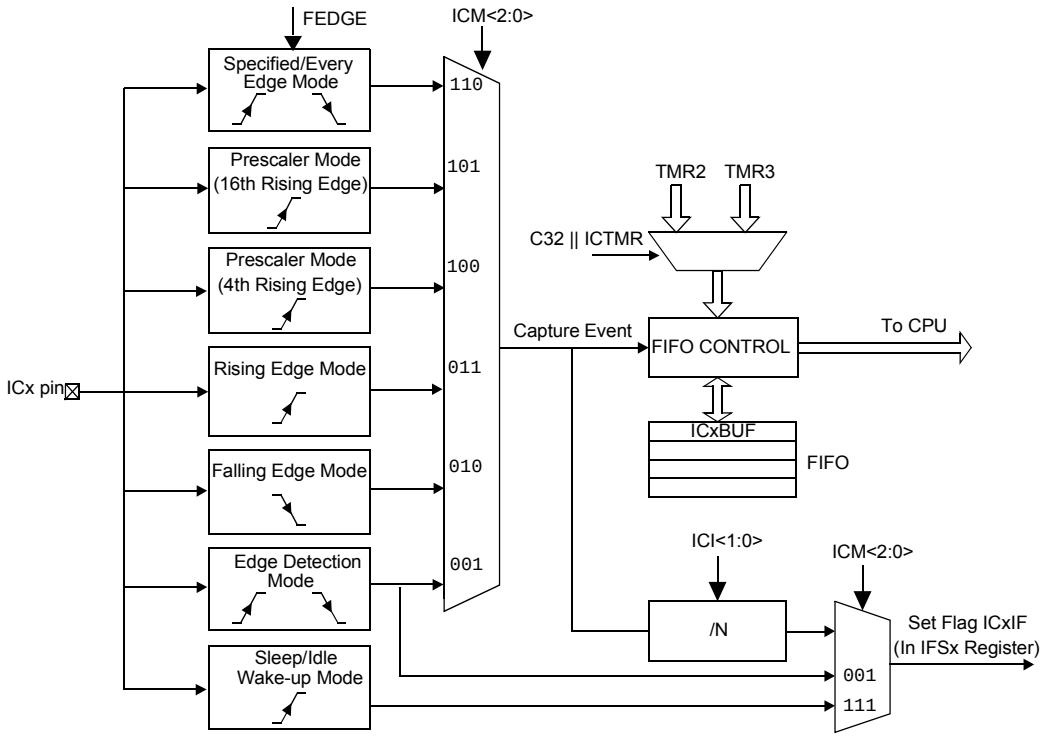
Each input capture channel can select between one of two 16-bit timers (Timer2 or Timer3) for the time base, or two 16-bit timers (Timer2 and Timer3) together to form a 32-bit timer. The selected timer can use either an internal or external clock.

Other operational features include:

- Device wake-up from capture pin during Sleep and Idle modes
- Interrupt on input capture event
- 4-word FIFO buffer for capture values (interrupt optionally generated after 1, 2, 3, or 4 buffer locations are filled)
- Input capture can also be used to provide additional sources of external interrupts

Figure 15-1 illustrates a general block diagram of the Input Capture module.

FIGURE 15-1: INPUT CAPTURE BLOCK DIAGRAM



Note: An 'x' in a signal, register or bit name denotes the number of the capture channel.

REGISTER 19-1: UxMODE: UARTx MODE REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	R/W-0	U-0	R/W-0	R/W-0	R/W-0	U-0	R/W-0	R/W-0
	ON(1)	—	SIDL	IREN	RTSMD	—	UEN<1:0>	
7:0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	WAKE	LPBACK	ABAUD	RXINV	BRGH	PDSEL<1:0>		STSEL

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-16 **Unimplemented:** Read as '0'

bit 15 **ON:** UARTx Enable bit(1)
- 1 = UARTx is enabled. UARTx pins are controlled by UARTx as defined by the UEN<1:0> and UTXEN control bits.
- 0 = UARTx is disabled. All UARTx pins are controlled by corresponding bits in the PORTx, TRISx and LATx registers; UARTx power consumption is minimal.

bit 14 **Unimplemented:** Read as '0'

bit 13 **SIDL:** Stop in Idle Mode bit
- 1 = Discontinue module operation when the device enters Idle mode
- 0 = Continue module operation when the device enters Idle mode

bit 12 **IREN:** IrDA Encoder and Decoder Enable bit
- 1 = IrDA is enabled
- 0 = IrDA is disabled

bit 11 **RTSMD:** Mode Selection for $\overline{\text{UxRTS}}$ Pin bit
- 1 = $\overline{\text{UxRTS}}$ pin is in Simplex mode
- 0 = $\overline{\text{UxRTS}}$ pin is in Flow Control mode

bit 10 **Unimplemented:** Read as '0'

bit 9-8 **UEN<1:0>:** UARTx Enable bits
- 11 = UxTX, UxRX and UxBCLK pins are enabled and used; $\overline{\text{UxCTS}}$ pin is controlled by corresponding bits in the PORTx register
- 10 = UxTX, UxRX, $\overline{\text{UxCTS}}$ and $\overline{\text{UxRTS}}$ pins are enabled and used
- 01 = UxTX, UxRX and $\overline{\text{UxRTS}}$ pins are enabled and used; $\overline{\text{UxCTS}}$ pin is controlled by corresponding bits in the PORTx register
- 00 = UxTX and UxRX pins are enabled and used; $\overline{\text{UxCTS}}$ and $\overline{\text{UxRTS}}$/UxBCLK pins are controlled by corresponding bits in the PORTx register

bit 7 **WAKE:** Enable Wake-up on Start bit Detect During Sleep Mode bit
- 1 = Wake-up enabled
- 0 = Wake-up disabled

bit 6 **LPBACK:** UARTx Loopback Mode Select bit
- 1 = Loopback mode is enabled
- 0 = Loopback mode is disabled

Note 1: When using 1:1 PBCLK divisor, the user software should not read/write the peripheral SFRs in the SYSCLK cycle immediately following the instruction that clears the module's ON bit.

REGISTER 27-2: DEVCFG1: DEVICE CONFIGURATION WORD 1

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	r-1	r-1	r-1	r-1	r-1	r-1	R/P	R/P
	—	—	—	—	—	—	FWDTWINSZ<1:0>	
23:16	R/P	R/P	r-1	R/P	R/P	R/P	R/P	R/P
	FWDTEN	WINDIS	—	WDTPS<4:0>				
15:8	R/P	R/P	R/P	R/P	r-1	R/P	R/P	R/P
	FCKSM<1:0>		FPBDIV<1:0>		—	OSCIOFNC	POSCMOD<1:0>	
7:0	R/P	r-1	R/P	r-1	r-1	R/P	R/P	R/P
	IESO	—	FSOSCEN	—	—	FNOSC<2:0>		

Legend:	r = Reserved bit	P = Programmable bit	
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-26 **Reserved:** Write '1'

bit 25-24 **FWDTWINSZ<1:0>:** Watchdog Timer Window Size bits
11 = Window size is 25%
10 = Window size is 37.5%
01 = Window size is 50%
00 = Window size is 75%

bit 23 **FWDTEN:** Watchdog Timer Enable bit
1 = Watchdog Timer is enabled and cannot be disabled by software
0 = Watchdog Timer is not enabled; it can be enabled in software

bit 22 **WINDIS:** Watchdog Timer Window Enable bit
1 = Watchdog Timer is in non-Window mode
0 = Watchdog Timer is in Window mode

bit 21 **Reserved:** Write '1'

bit 20-16 **WDTPS<4:0>:** Watchdog Timer Postscale Select bits
10100 = 1:1048576
10011 = 1:524288
10010 = 1:262144
10001 = 1:131072
10000 = 1:65536
01111 = 1:32768
01110 = 1:16384
01101 = 1:8192
01100 = 1:4096
01011 = 1:2048
01010 = 1:1024
01001 = 1:512
01000 = 1:256
00111 = 1:128
00110 = 1:64
00101 = 1:32
00100 = 1:16
00011 = 1:8
00010 = 1:4
00001 = 1:2
00000 = 1:1
All other combinations not shown result in operation = 10100

Note 1: Do not disable the POSC (POSCMOD = 11) when using this oscillator source.

TABLE 30-6: DC CHARACTERISTICS: IDLE CURRENT (IIDLE)

DC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp			
Parameter No.	**Typical(2)**	**Max.**	**Units**	**Conditions**		
Idle Current (IIDLE): Core Off, Clock on Base Current (Notes 1, 4)						
DC30a	1	1.5	mA	4 MHz **(Note 3)**		
DC31a	2	3	mA	10 MHz		
DC32a	4	6	mA	20 MHz **(Note 3)**		
DC33a	5.5	8	mA	30 MHz **(Note 3)**		
DC34a	7.5	11	mA	40 MHz		
DC37a	100	—	µA	-40°C	3.3V	LPRC (31 kHz) **(Note 3)**
DC37b	250	—	µA	+25°C		
DC37c	380	—	µA	+85°C		

Note 1: The test conditions for IIDLE current measurements are as follows:

- Oscillator mode is EC (for 8 MHz and below) and EC+PLL (for above 8 MHz) with OSC1 driven by external square wave from rail-to-rail, (OSC1 input clock input over/undershoot < 100 mV required)
- OSC2/CLKO is configured as an I/O input pin
- USB PLL oscillator is disabled if the USB module is implemented, PBCLK divisor = 1:8
- CPU is in Idle mode (CPU core Halted), and SRAM data memory Wait states = 1
- No peripheral modules are operating, (ON bit = 0), but the associated PMD bit is cleared
- WDT, Clock Switching, Fail-Safe Clock Monitor, and Secondary Oscillator are disabled
- All I/O pins are configured as inputs and pulled to VSS
- $\overline{MCLR}$ = VDD
- RTCC and JTAG are disabled

2: Data in the "Typical" column is at 3.3V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

3: This parameter is characterized, but not tested in manufacturing.

4: IIDLE electrical characteristics for devices with 256 KB Flash are only provided as Preliminary information.

TABLE 30-12: DC CHARACTERISTICS: PROGRAM MEMORY

DC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param. No.	**Symbol**	**Characteristics**	**Min.**	**Typical(1)**	**Max.**	**Units**	**Conditions**
		Program Flash Memory(3)					
D130	EP	Cell Endurance	20,000	—	—	E/W	—
D131	VPR	VDD for Read	2.3	—	3.6	V	—
D132	VPEW	VDD for Erase or Write	2.3	—	3.6	V	—
D134	TRETD	Characteristic Retention	20	—	—	Year	Provided no other specifications are violated
D135	IDDP	Supply Current during Programming	—	10	—	mA	—
	TWW	Word Write Cycle Time	—	411	—	FRC Cycles	See **Note 4**
D136	TRW	Row Write Cycle Time	—	6675	—		See **Note 2,4**
D137	TPE	Page Erase Cycle Time	—	20011	—		See **Note 4**
	TCE	Chip Erase Cycle Time	—	80180	—		See **Note 4**

Note 1: Data in "Typical" column is at 3.3V, 25°C unless otherwise stated.

2: The minimum SYSCLK for row programming is 4 MHz. Care should be taken to minimize bus activities during row programming, such as suspending any memory-to-memory DMA operations. If heavy bus loads are expected, selecting Bus Matrix Arbitration mode 2 (rotating priority) may be necessary. The default Arbitration mode is mode 1 (CPU has lowest priority).

3: Refer to the *"PIC32 Flash Programming Specification"* (DS60001145) for operating conditions during programming and erase cycles.

4: This parameter depends on FRC accuracy (See Table 30-19) and FRC tuning values (See Register 8-2).

TABLE 30-13: COMPARATOR SPECIFICATIONS

DC CHARACTERISTICS			Standard Operating Conditions (see Note 4): 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param. No.	**Symbol**	**Characteristics**	**Min.**	**Typical**	**Max.**	**Units**	**Comments**
D300	VIOFF	Input Offset Voltage	—	±7.5	±25	mV	AVDD = VDD, AVSS = VSS
D301	VICM	Input Common Mode Voltage	0	—	VDD	V	AVDD = VDD, AVSS = VSS **(Note 2)**
D302	CMRR	Common Mode Rejection Ratio	55	—	—	dB	Max VICM = (VDD - 1)V **(Note 2)**
D303A	TRESP	Large Signal Response Time	—	150	400	ns	AVDD = VDD, AVSS = VSS **(Note 1,2)**
D303B	TSRESP	Small Signal Response Time	—	1	—	μs	This is defined as an input step of 50 mV with 15 mV of overdrive **(Note 2)**
D304	ON2OV	Comparator Enabled to Output Valid	—	—	10	μs	Comparator module is configured before setting the comparator ON bit **(Note 2)**
D305	IVREF	Internal Voltage Reference	1.14	1.2	1.26	V	—
D312	TSET	Internal Comparator Voltage DRC Reference Setting time	—	—	10	μs	**(Note 3)**

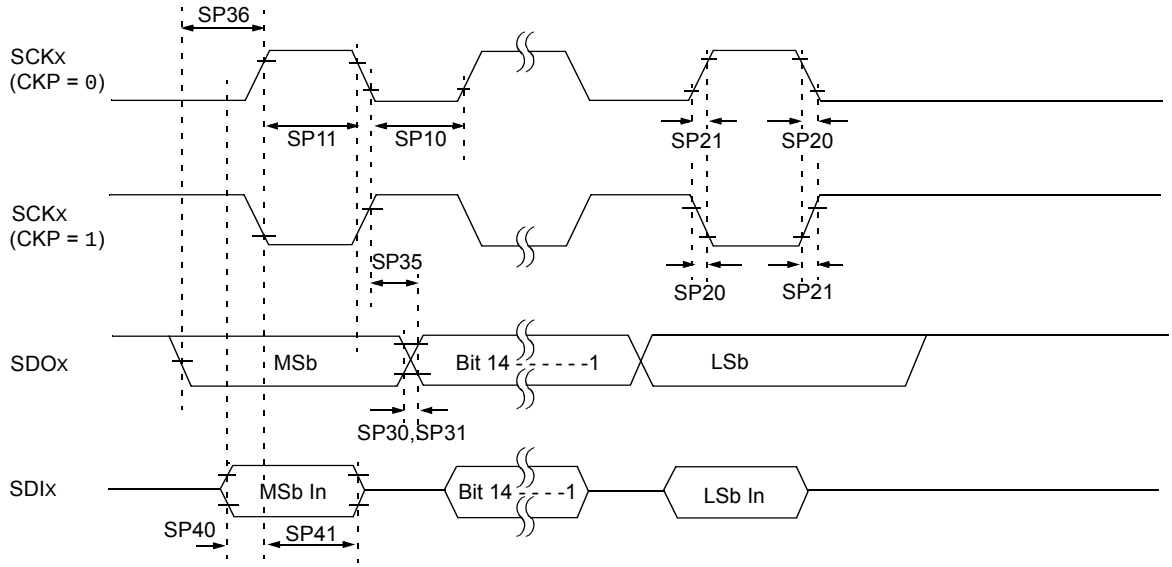
Note 1: Response time measured with one comparator input at (VDD – 1.5)/2, while the other input transitions from VSS to VDD.

2: These parameters are characterized but not tested.

3: Settling time measured while CVRR = 1 and CVR<3:0> transitions from '0000' to '1111'. This parameter is characterized, but not tested in manufacturing.

4: The Comparator module is functional at VBORMIN < VDD < VDDMIN, but with degraded performance. Unless otherwise stated, module functionality is tested, but not characterized.

FIGURE 30-11: SPIx MODULE MASTER MODE (CKE = 1) TIMING CHARACTERISTICS



Note: Refer to Figure 30-1 for load conditions.

TABLE 30-29: SPIx MODULE MASTER MODE (CKE = 1) TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param. No.	**Symbol**	**Characteristics(1)**	**Min.**	**Typ.(2)**	**Max.**	**Units**	**Conditions**
SP10	TscL	SCKx Output Low Time **(Note 3)**	Tsck/2	—	—	ns	—
SP11	TscH	SCKx Output High Time **(Note 3)**	Tsck/2	—	—	ns	—
SP20	TscF	SCKx Output Fall Time **(Note 4)**	—	—	—	ns	See parameter DO32
SP21	TscR	SCKx Output Rise Time **(Note 4)**	—	—	—	ns	See parameter DO31
SP30	TdoF	SDOx Data Output Fall Time **(Note 4)**	—	—	—	ns	See parameter DO32
SP31	TdoR	SDOx Data Output Rise Time **(Note 4)**	—	—	—	ns	See parameter DO31
SP35	TscH2doV, TscL2doV	SDOx Data Output Valid after SCKx Edge	—	—	15	ns	VDD > 2.7V
			—	—	20	ns	VDD < 2.7V
SP36	TdoV2sc, TdoV2scL	SDOx Data Output Setup to First SCKx Edge	15	—	—	ns	—
SP40	TdiV2scH, TdiV2scL	Setup Time of SDIx Data Input to SCKx Edge	15	—	—	ns	VDD > 2.7V
			20	—	—	ns	VDD < 2.7V
SP41	TscH2diL, TscL2diL	Hold Time of SDIx Data Input to SCKx Edge	15	—	—	ns	VDD > 2.7V
			20	—	—	ns	VDD < 2.7V

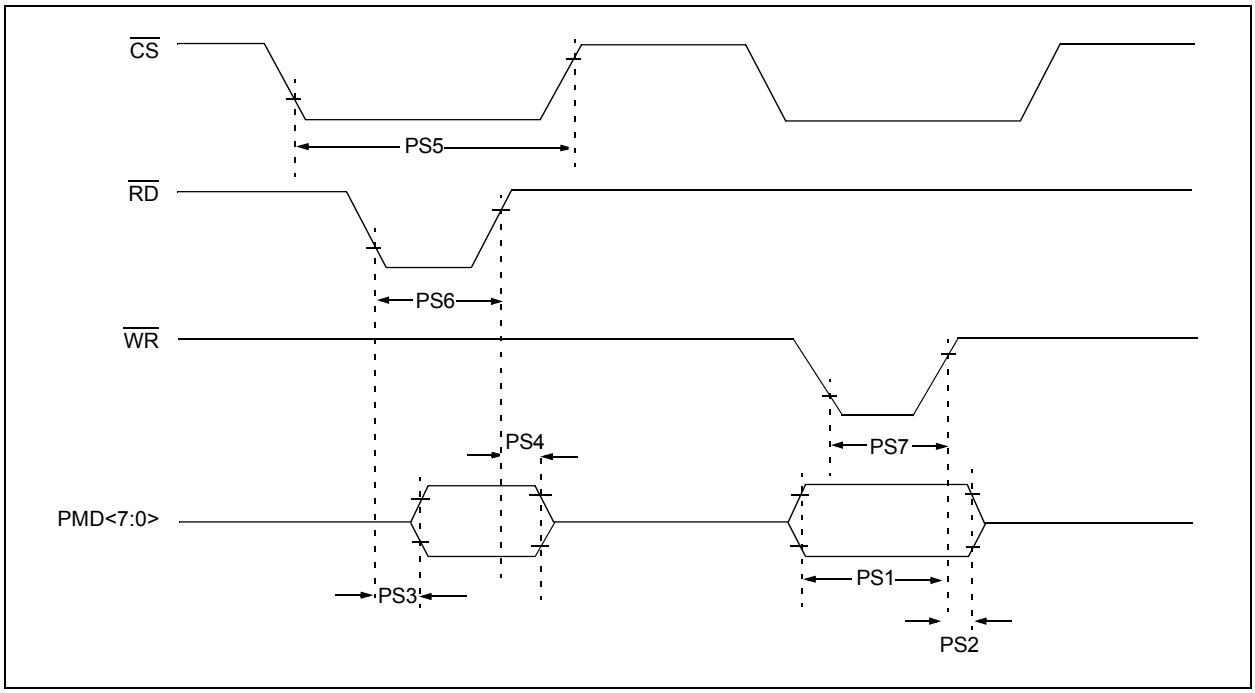
Note 1: These parameters are characterized, but not tested in manufacturing.

2: Data in "Typical" column is at 3.3V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

3: The minimum clock period for SCKx is 50 ns. Therefore, the clock generated in Master mode must not violate this specification.

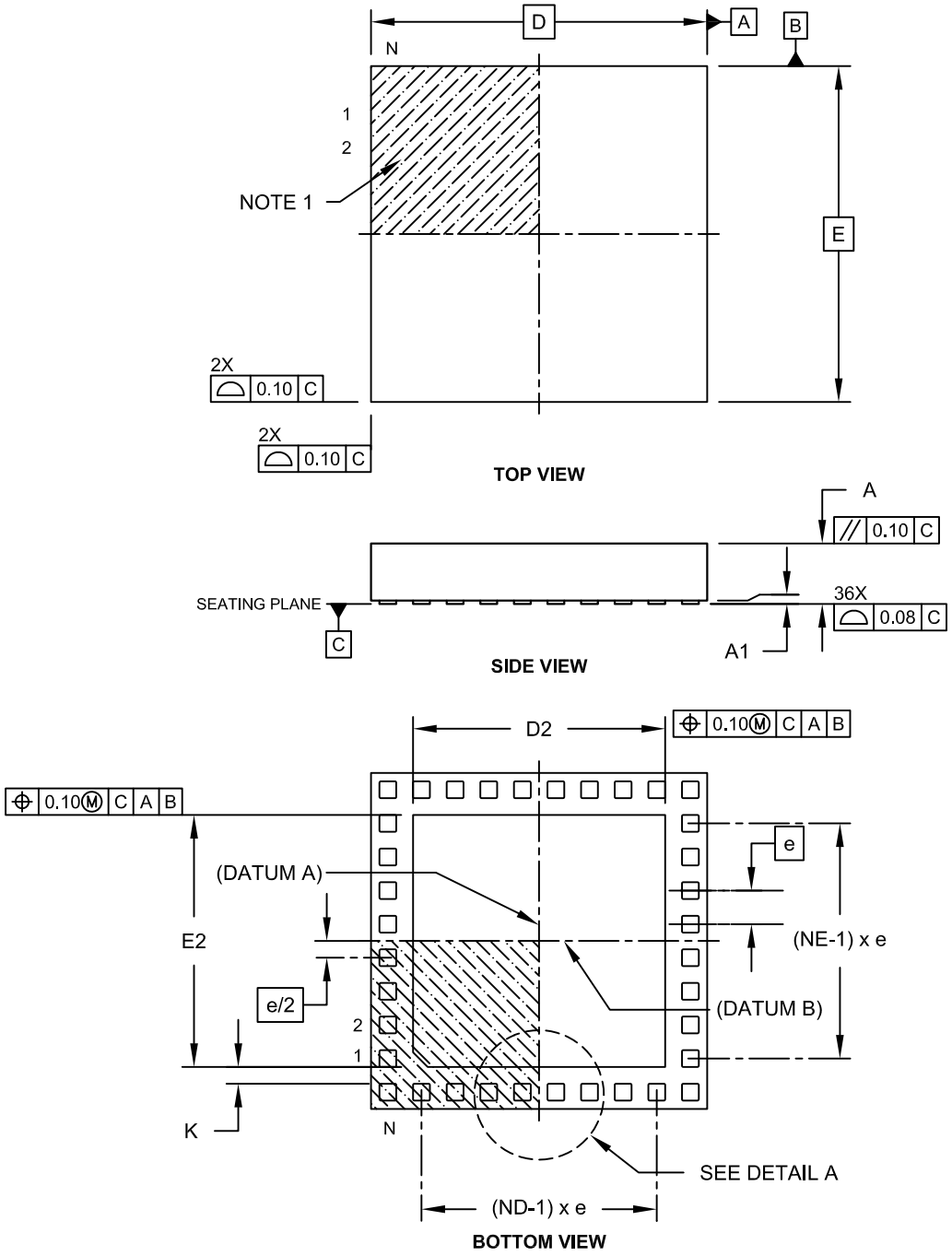
4: Assumes 50 pF load on all SPIx pins.

FIGURE 30-20: PARALLEL SLAVE PORT TIMING



36-Terminal Very Thin Thermal Leadless Array Package (TL) – 5x5x0.9 mm Body with Exposed Pad [VTLA]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Microchip Technology Drawing C04-187C Sheet 1 of 2